L Number	Hits	Search Text	DB	Time stamp
1	2	5738797.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/09 14:03
2	3	4404059.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/09 14:03
3	3	3801388.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/09 14:47
4	18	pcb and pre near circuit and hole and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/09 15:04
5	3320	pcb and through adj hole and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/09 15:04
6	12	pcb and through adj hole and solder and pre near circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/09 15:05
7	51	pcb and through adj hole and solder and 29/830.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/09 15:24
8	298	pcb and through adj hole and solder and (29/830; 29/851 ; 29/852 ; 174/255-259 ; 174/261-266 ; 361/792-795 ; 428/901).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/09 15:10
9	0	pcb and through adj hole and solder and precircuit and (29/830; 29/851 ; 29/852 ; 174/255-259 ; 174/261-266 ; 361/792-795 ; 428/901).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/09 15:10
10	0	pcb and through adj hole and solder and precircuit and (29/830; 29/851 ; 29/852 ; 174/255-259 ; 174/261; 361/792-795 ; 428/901).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/09 15:10

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11	1	pcb and through adj hole and solder and pre near circuit and (29/830; 29/851 ; 29/852 ; 174/255-259 ; 174/261; 361/792-795 ; 428/901).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/09 15:10
12	6	("3526867" | "3801388" | "4404059" | "5477086" | "5889657" | "6111204").PN.	USPAT	2004/09/09 15:13
13	4	("3801388" | "4404059" | "4561173" | "5738797").PN.	USPAT	2004/09/09 15:14
14	5	("3801388" | "4404059" | "4710419" | "4944908" | "5220488").PN.	USPAT	2004/09/09 15:15
15	63	4404059.URPN.	USPAT	2004/09/09 15:17
16	6	("3801388" | "4404059" | "4528064" | "H001471" | "5451721" | "5738797").PN.	USPAT	2004/09/09 15:18
17	333	pcb and through adj hole and solder and (216/13; 216/15 ; 216/17 ; 216/18 ; 216/19 ; 174/250 ; 174/261; 174/262 ; 174/263 ; 174/255 ; 29/830 ; 29/831 ; 29/832; 29/846 ; 29/847).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/09 16:12
18	10	("4803450" | "5031308" | "5048166" | "5199163" | "5220723" | "5285570" | "5384955" | "5386627" | "5403671" | "5509200").PN.	USPAT	2004/09/09 15:35
19	0	pcb and through adj hole and solder and pre adj circuit and (216/13; 216/15 ; 216/17 ; 216/18 ; 216/19 ; 174/250 ; 174/261; 174/262 ; 174/263 ; 174/255 ; 29/830 ; 29/831 ; 29/832; 29/846 ; 29/847).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/09 16:13
20	1	pcb and through adj hole and solder and pre near circuit and (216/13; 216/15 ; 216/17 ; 216/18 ; 216/19 ; 174/250 ; 174/261; 174/262 ; 174/263 ; 174/255 ; 29/830 ; 29/831 ; 29/832; 29/846 ; 29/847).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/09 16:13